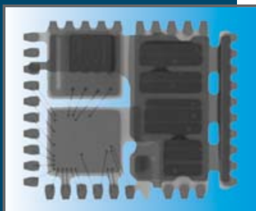
Advanced Packaging Update:
Market and Technology Trends

Vol. 1-0422



This issue of the Advanced Packaging Update features a detailed OSAT financial analysis. A special section examines the impact of the war in Ukraine and China's lockdowns. The expansion of cryptocurrency and its impact on energy consumption and packaging and assembly services are discussed. Market drivers and forecasts for Ball Grid Arrays (BGAs) and Chip Scaled Packages (CSPs) are provided. The CSP market is divided into laminate (FBGA and FLGA) substrates and leadframes (QFN). Stacked die package trends are included. Unit growth projections for Cu clip and molded interconnect substrates (MIS) are provided.

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Single issue – $2,500
Corporate license – $8,750 (4 issues)

Contents and specifications subject to change without notice. 05/27/22